



SOT189-3

plastic leaded chip carrier; 84 leads; pedestal, 1.27 mm pitch,
29.24 mm x 29.24 mm x 3.68 mm body

11 October 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	PLCC84
Package type industry code	PLCC84
Package style descriptive code	PLCC (plastic leaded chip carrier)
Package body material type	P (plastic)
IEC package outline code	112E13
JEDEC package outline code	MO-047
Mounting method type	S (surface mount)
Issue date	14-11-2001
Manufacturer package code	SOT189

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	29.21	29.31	29.41	mm
package width	29.21	29.31	29.41	mm
seated height	4.19	4.38	4.57	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	84	-	



2 Package outline

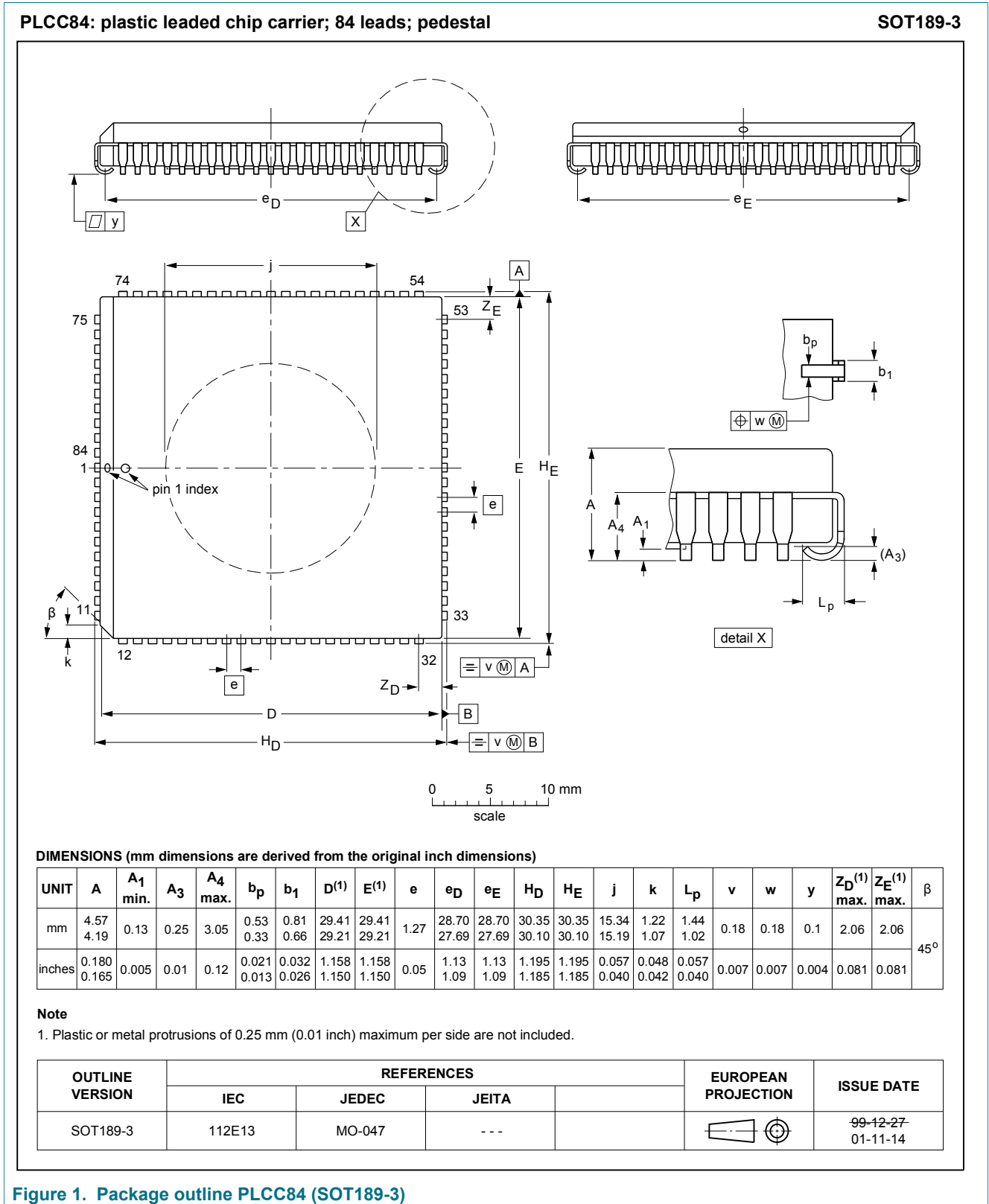
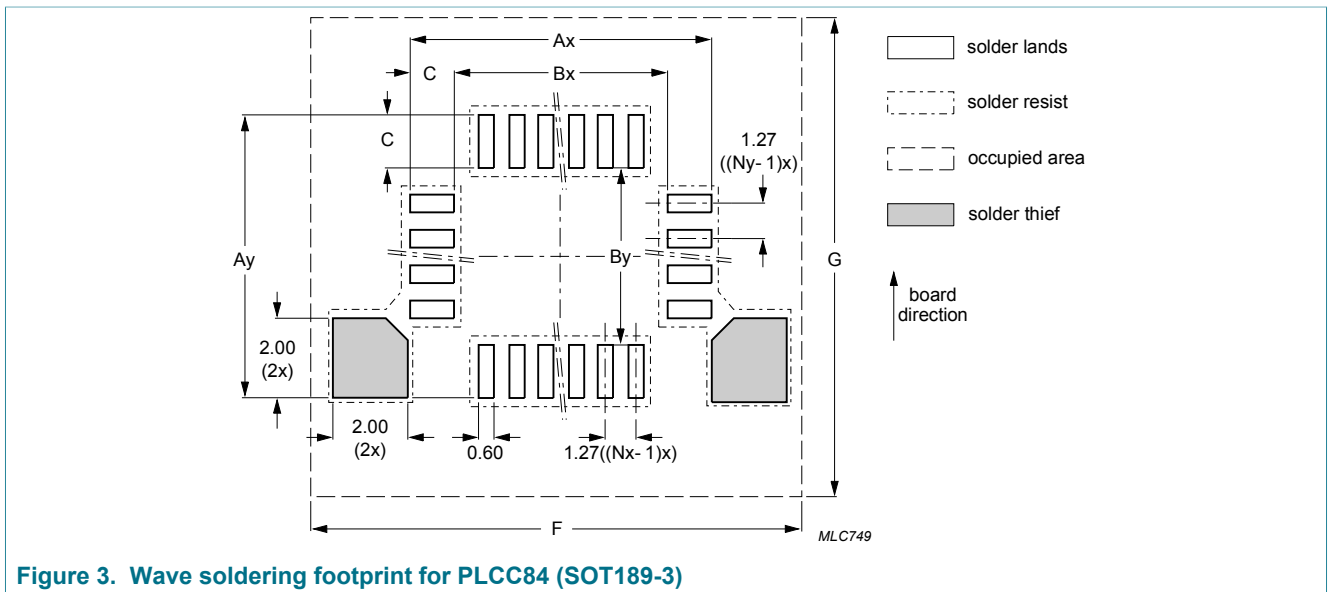
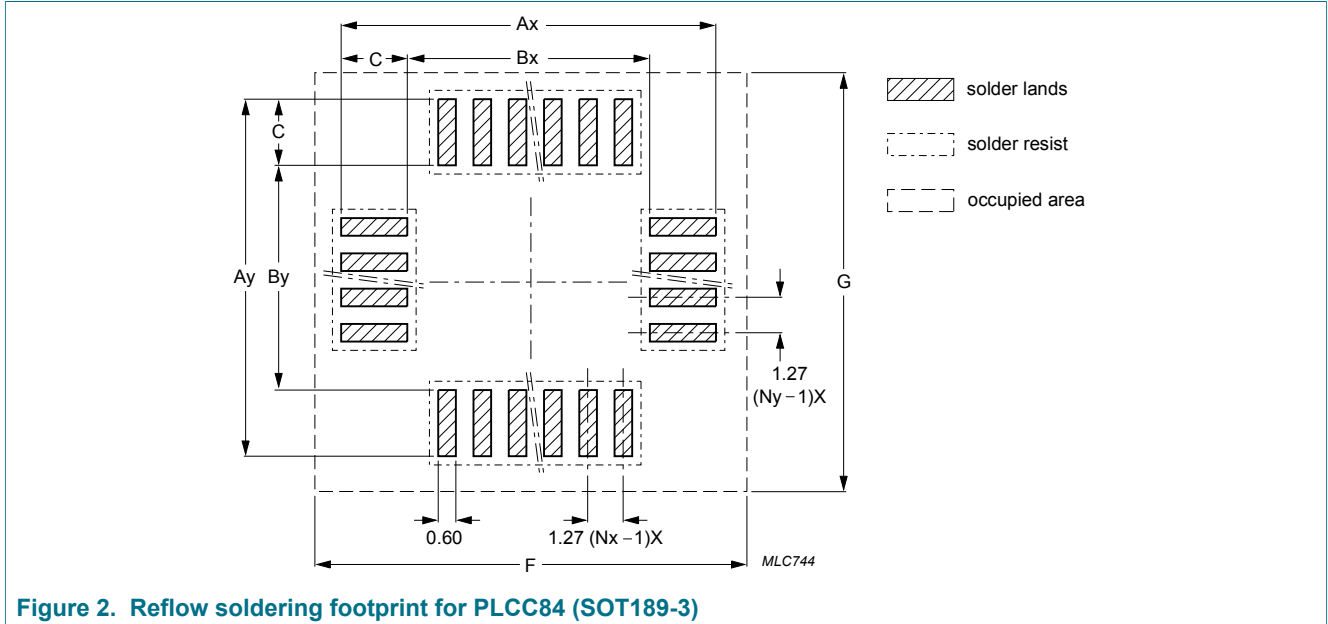


Figure 1. Package outline PLCC84 (SOT189-3)

3 Soldering



4 Legal information

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